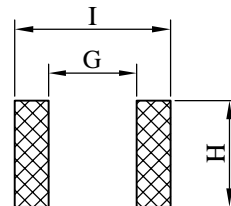
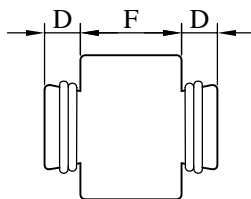
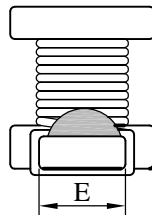
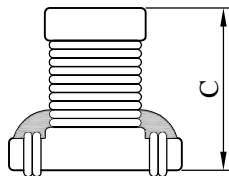
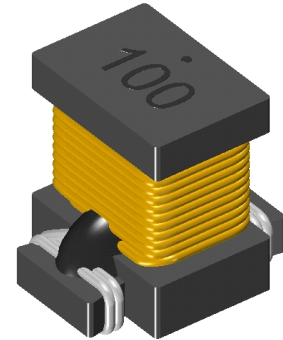
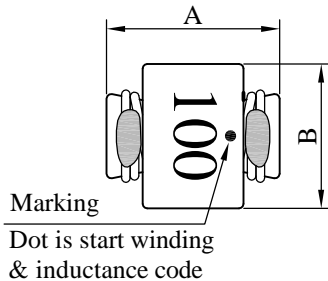


SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	SMD Power Inductor	ABC'S DWG NO.	SQ0504□□□□L□-□□□		
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I . Configuration and dimensions :



(PCB Pattern)

Unit : m/m

A	B	C	D	E	F	G	H	I
4.80 ±0.3	4.00 ±0.3	4.50 ±0.3	1.00 typ.	2.40 typ.	2.80 typ.	2.00 ref.	2.80 ref.	4.80ref.

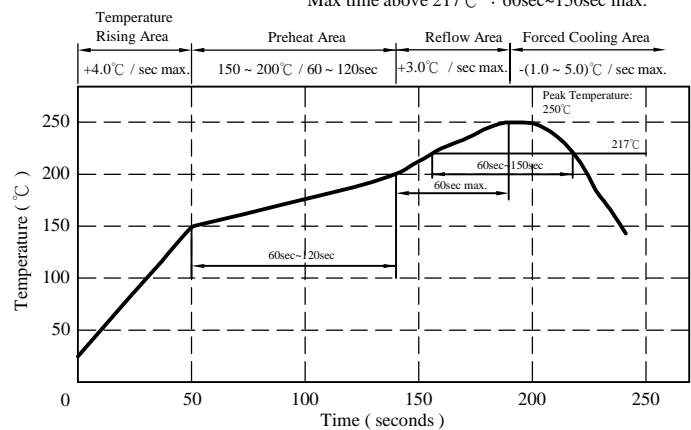
II . Description :

- a . Ferrite drum core construction.
- b . Enamelled copper wire : F class
- c . Product weight : 0.25g (ref.)
- d . Moisture sensitivity Level 1
- e . Products comply with RoHS' requirements
- f . Halogen free available

Peak Temp : 250°C max.
Max. Peak Temp - 5°C : 30sec max.
Max time above 217°C : 60sec~150sec max.

III . General specification :

- a . Storage temp. : -40°C ----+125°C
- b . Operating temp. : -40°C ----+125°C
(Temp. rise included)
- c . Resistance to solder heat : 250°C .10 secs.



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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	SMD Power Inductor	ABC'S DWG NO.	SQ0504□□□□L□-□□□		
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IV . Electrical characteristics :

DWG No.	Inductance (uH)	Q ref.	Test Freq.(Hz)		SRF (MHz) typ.	RDC(Ω)		Irms (mA) typ.	Isat (mA) typ.
			L	Q		typ.	max.		
SQ05042R2ML□-□□□	2.2 ±20%	35	100k	7.96M	70.0	0.032	0.043	2600	2400
SQ05043R3ML□-□□□	3.3 ±20%	32	100k	7.96M	40.0	0.043	0.058	2300	2000
SQ05044R7ML□-□□□	4.7 ±20%	25	100k	7.96M	30.0	0.050	0.068	2100	1800
SQ0504100ML□-□□□	10.0 ±20%	32	100k	2.52M	26.0	0.110	0.145	1500	1150
SQ0504220ML□-□□□	22.0 ±20%	30	100k	2.52M	13.0	0.250	0.315	950	800
SQ0504330ML□-□□□	33.0 ±20%	28	100k	2.52M	10.0	0.400	0.500	700	650
SQ0504470ML□-□□□	47.0 ±20%	26	100k	2.52M	7.0	0.525	0.660	580	550
SQ0504101KL□-□□□	100.0 ±10%	40	100k	796k	6.5	1.000	1.250	430	370
SQ0504221KL□-□□□	220.0 ±10%	40	100k	796k	4.0	2.200	2.750	290	270
SQ0504331KL□-□□□	330.0 ±10%	40	100k	796k	3.5	3.250	4.050	230	210
SQ0504471KL□-□□□	470.0 ±10%	40	100k	796k	3.2	5.200	6.500	200	170

- 1). □: Packaging information : □ Code
- 2). "-□□□" : Reference code
- 3). Electrical specifications at 25°C
- 4). Isat base on $\Delta L/L0A=10\%$ typ.
- 5). Irms base on Temp. rise 40°C typ.
- 6). Inductance Test Freq. 100kHz/0.1V

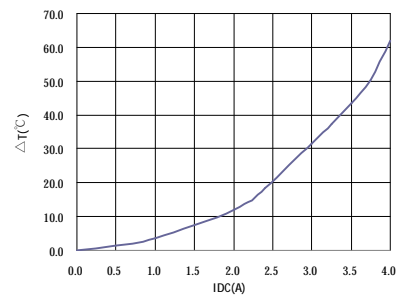
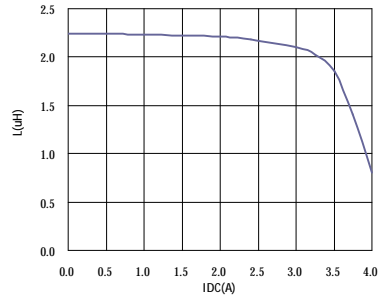
SPECIFICATION FOR APPROVAL

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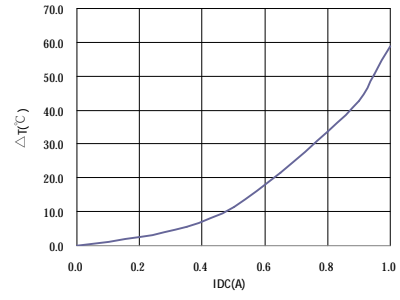
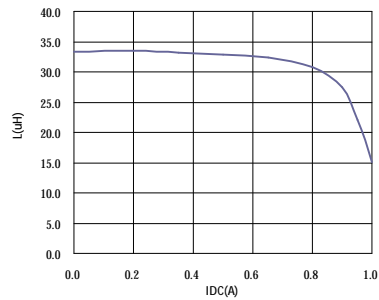
PROD. NAME	SMD Power Inductor	ABC'S DWG NO.		SQ0504□□□□L□-□□□	
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V . Curve :

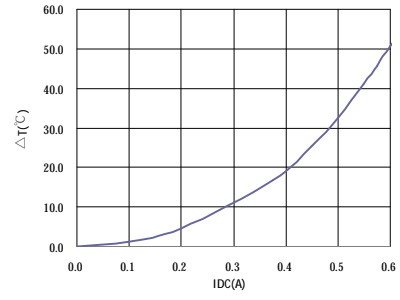
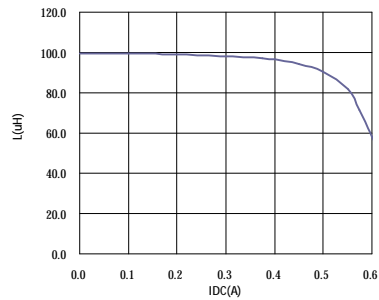
SQ05042R2ML□



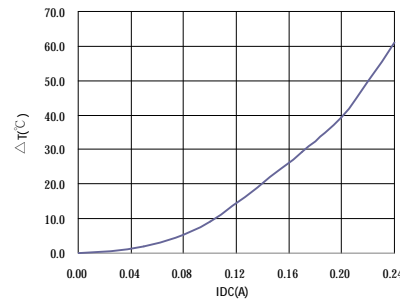
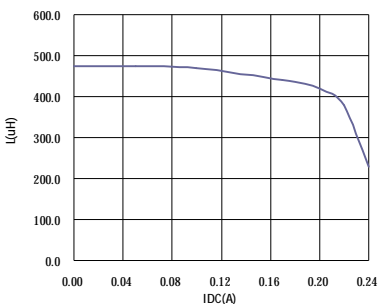
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SQ0504101KL□



SQ0504471KL□



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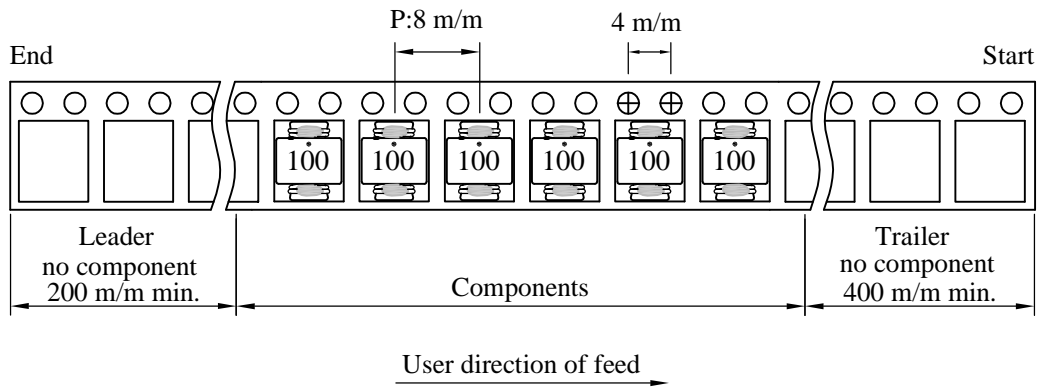
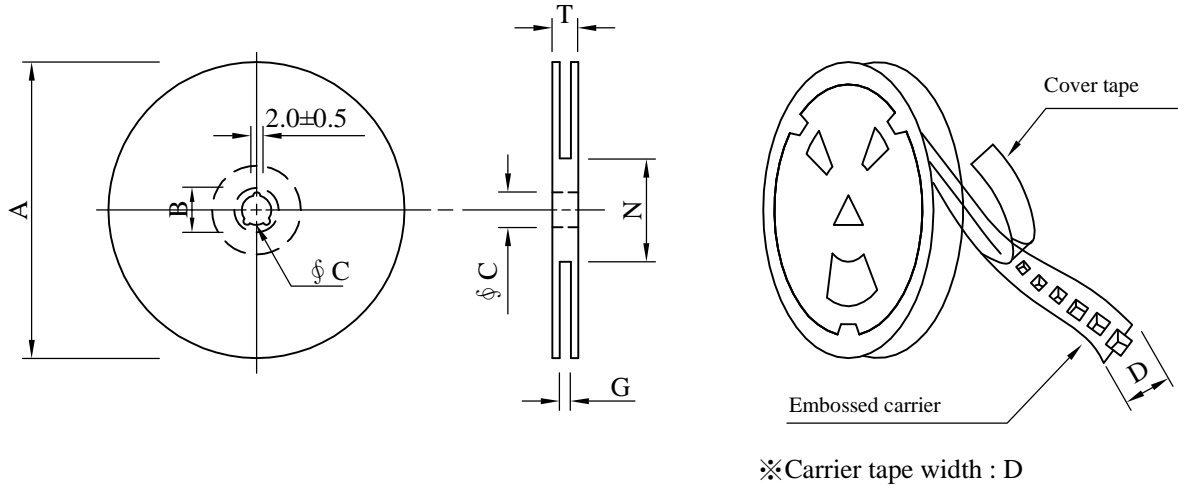
SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	SMD Power Inductor	ABC'S DWG NO.	SQ0504□□□□L□-□□□		
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VI . Packaging information :

(1) Configuration



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
13 - 16	330	21±0.8	13±0.5	16	18 ⁺⁰	50 ⁻⁰	22.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
B	1,200	730	13 - 16	7,200	5.6	38 x 37 x 22

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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	SMD Power Inductor	ABC'S DWG NO.	SQ0504□□□□L□-□□□		
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VII . Reliability test :

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature : 85±2 ℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃ (Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in apperance. 2.No marking blurred. 3.Inductance shall not change more than ±10%.
8. Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature : 250±5℃. 2.Time (temp. ≥ 217℃) : 60~150 Second. 3.IR reflow times : 3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 second. 2.Saturation current	Inductance shall not drop more than 10% typ.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 40 °C typ.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing : 150±5℃ / 16Hours±30 min. 2.Peak temperature : 240±5℃ 3.Time (temp. ≥ 217℃) : 60~150 second. 4.IR reflow times : 1 times.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature : -40℃~125℃ 2.Room temperature : 25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. PCB and dropped down from a height of 1m 2.Drop total time : 6 time (Every side of sample drop 2 time)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.

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